Title (en)

MATERIALS FOR ELECTRONIC DEVICES

Title (de)

MATERIALIEN FÜR ELEKTRONISCHE VORRICHTUNGEN

Title (fr)

MATÉRIAUX POUR DISPOSITIFS ÉLECTRONIQUES

Publication

EP 4240718 A1 20230913 (DE)

Application

EP 21766618 A 20210824

Priority

- EP 20205399 A 20201103
- EP 2021073322 W 20210824

Abstract (en)

[origin: WO2022096172A1] The present invention relates to compounds of a formula (I) or (II), processes for preparing compounds of this type, electronic devices containing one or more of these compounds, and the use of these compounds in electronic devices.

IPC 8 full level

C07C 211/61 (2006.01); **C07D 209/86** (2006.01); **C07D 307/91** (2006.01); **C07D 333/76** (2006.01); **C09K 11/06** (2006.01)

CPC (source: EP KR US)

C07C 211/61 (2013.01 - EP KR US); **C07D 209/86** (2013.01 - EP KR); **C07D 209/88** (2013.01 - US); **C07D 307/91** (2013.01 - EP KR US); **C07D 333/76** (2013.01 - EP); **C09K 11/06** (2013.01 - EP KR US); **H10K 50/11** (2023.02 - KR); **H10K 85/631** (2023.02 - EP); **H10K 85/633** (2023.02 - KR US); **H10K 85/636** (2023.02 - KR US); **H10K 85/6572** (2023.02 - KR); **H10K 85/6574** (2023.02 - EP KR); C07B 2200/05 (2013.01 - EP KR); C07C 2603/18 (2017.05 - EP KR US); C07C 2603/94 (2017.05 - EP KR); C07C 2603/97 (2017.05 - US); C09K 2211/1007 (2013.01 - US); C09K 2211/1011 (2013.01 - US); C09K 2211/1014 (2013.01 - US); C09K 2211/1018 (2013.01 - US); H10K 50/15 (2023.02 - EP); H10K 50/181 (2023.02 - EP KR US); H10K 85/624 (2023.02 - US); H10K 85/626 (2023.02 - US); H10K 85/6572 (2023.02 - US); H10K 85/6574 (2023.02 - US); Y02E 10/549 (2013.01 - EP)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

WO 2022096172 A1 20220512; CN 116323559 A 20230623; EP 4240718 A1 20230913; KR 20230104195 A 20230707; TW 202233565 A 20220901; US 2023413662 A1 20231221

DOCDB simple family (application)

EP 2021073322 W 20210824; CN 202180071384 A 20210824; EP 21766618 A 20210824; KR 20237018294 A 20210824; TW 110140347 A 20211029; US 202118034891 A 20210824